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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yuichi INADA, et al.

Group Art Unit: 1722

Serial No. 10/534,488

Examiner: Bodawala, Dimple N.

Filed: May 11, 2005

Atty. Docket No.: 59559.00020

For: MOLDING DIE, MOLDING METHOD, DISC SUBSTRATE, AND MOLDING MACHINE

**RESPONSE TO RESTRICTION REQUIREMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 14, 2007

Sir:

In response to the Office Action dated January 22, 2007, please consider the following remarks.

Remarks are submitted beginning on page 2.